



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ CSP CHIP LED
- ▶ 1111 0.35t Series
- ▶ Natural White (4000K)

NOW53S67



Release Date: 27 September 2021 Version: A1.4



1111 0.35t Series

RoHS Compliant



FEATURES:

- **Package:** Ceramic High Power CSP Package
- **Forward Current:** 500mA
- **Forward Voltage (typ.):** 3.1V
- **Luminous Flux (typ.):** 170lm@500mA
- **Colour:** Natural White
- **CCT/Colour Temperature (typ.):** 4000K
- **Viewing angle:** 120°
- **Materials:**
 - Die: Flip-Chip InGaN
 - Resin: Silicon (Yellow Diffused)
 - L/T Finish: Au plated on AlN
- **Operating Temperature:** -30~+85°C
- **Storage Temperature:** -40~+125°C
- **Grouping parameters:**
 - Forward Voltage
 - Luminous Flux
 - CIE Chromaticity
- **Soldering Method:** IR Reflow
- **Recommended Soldering Paste:** SAC305
- **Preconditioning:** MSL2 according to J-STD020
- **Packing:** 8mm tape with Min.1000pcs /reel, ø180mm (7")

APPLICATIONS:

- Decorative Lighting
- Portable Lighting
- Outdoor Lighting
- Commercial Lighting
- Indoor Lighting
- Industrial Lighting

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	600	mA
Peak Pulsed Current (<100ms) *	I _{PF}	900	mA
Power Dissipation	P _D	2.03	W
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	150	°C
Thermal Resistance Junction to Case	R _{th(j-c)}	2.6	°C/W
Operating Temperature	T _{OPR}	-30~+85	°C
Storage Temperature	T _{STG}	-40~+125	°C
Colour Rendering Index / Ra	CRI	70	---

* 1/10 duty cycle @1KHz

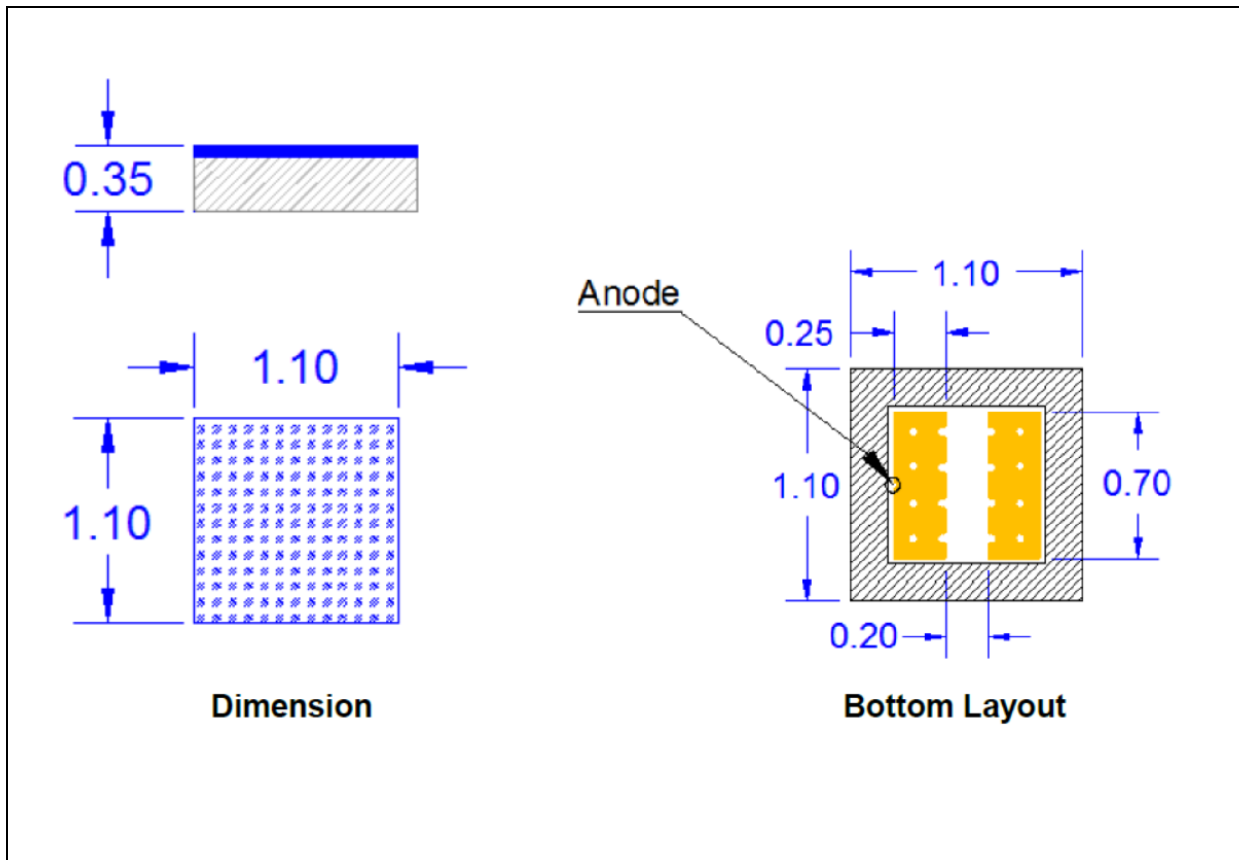
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	3.0	3.1	3.4	V	I _F =500mA
Luminous Flux	Φ _V	150	170	190	lm	I _F =500mA
Chromaticity Coordinates	X	0.3670	---	0.4006	---	I _F =500mA
	Y	0.3578	---	0.4044		
CCT	---	---	4000	---	K	I _F =500mA
Viewing Angle	2θ _{1/2}	---	120	---	deg	I _F =500mA

1. Luminous flux (Φ_V) ±7%, Forward Voltage (V_F) ±0.05V, Viewing angle(2θ_{1/2}) ±10°, CRI ±2

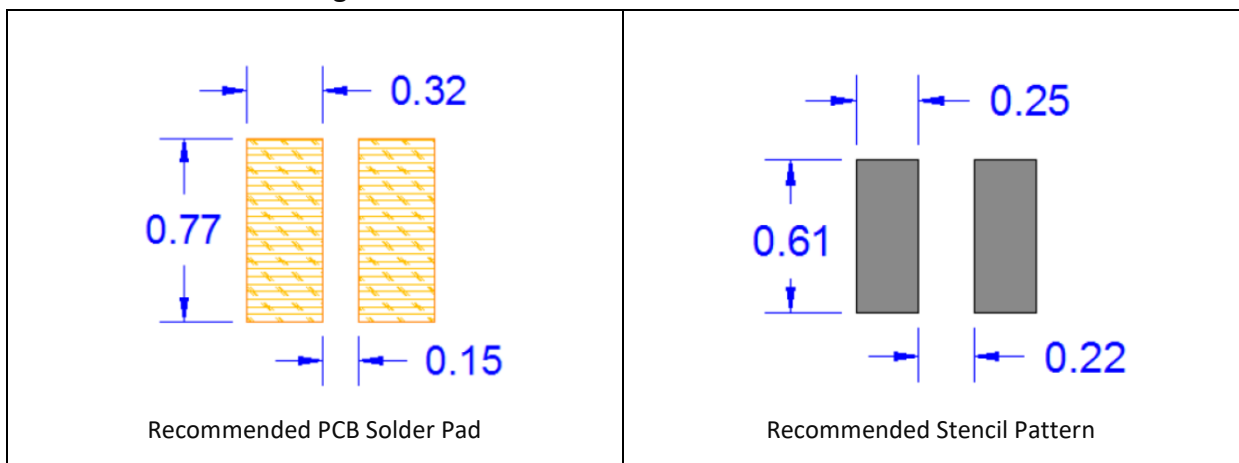
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.13\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.12\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

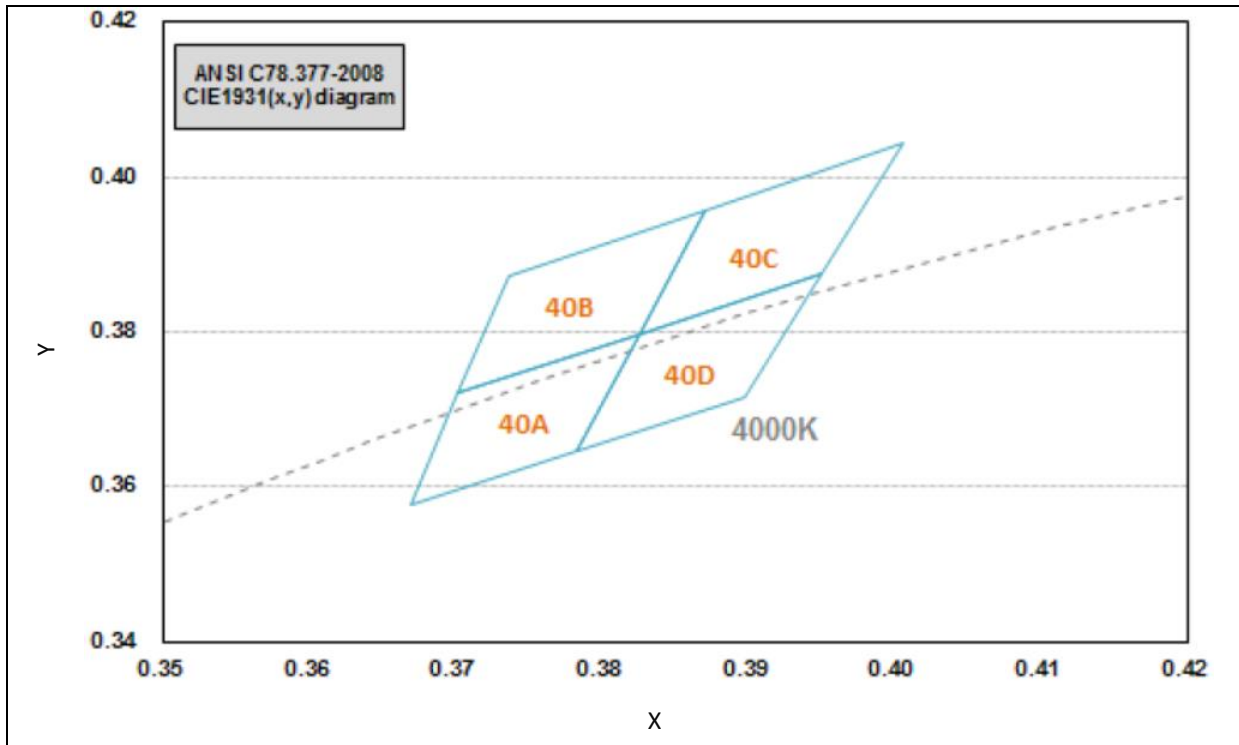
 Forward Voltage Classifications ($I_F = 500\text{mA}$):

Code	Min.	Max.	Unit
AA	3.0	3.1	V
AB	3.1	3.2	
AC	3.2	3.3	
AD	3.3	3.4	

 Luminous Flux Classifications ($I_F = 500\text{mA}$):

Code	Min.	Max.	Unit
C15	150	160	lm
C16	160	170	
C17	170	180	
C18	180	190	

CIE CHROMATICITY DIAGRAM:

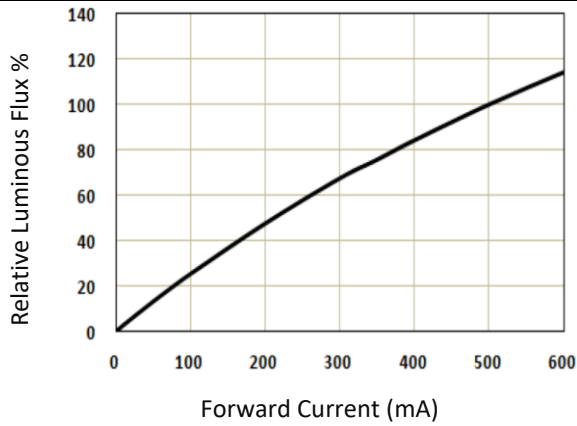


Chromaticity Coordinates Classifications ($I_F = 500\text{mA}$):

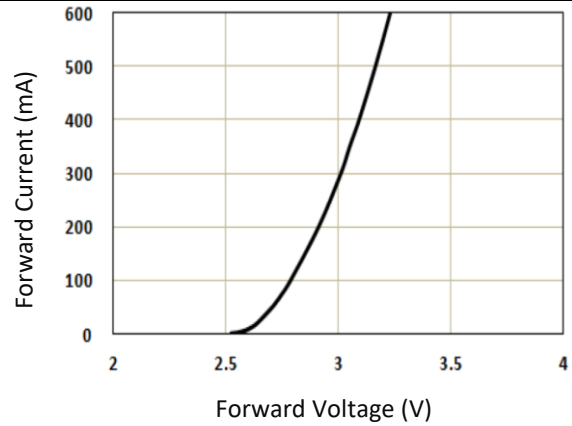
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
40A	0.3670	0.3578	0.3702	0.3722	0.3825	0.3798	0.3783	0.3646
40B	0.3702	0.3722	0.3736	0.3874	0.3870	0.3958	0.3825	0.3798
40C	0.3825	0.3798	0.3870	0.3958	0.4006	0.4044	0.3951	0.3876
40D	0.3783	0.3646	0.3825	0.3798	0.3951	0.3876	0.3898	0.3716

ELECTRO-OPTICAL CHARACTERISTICS:

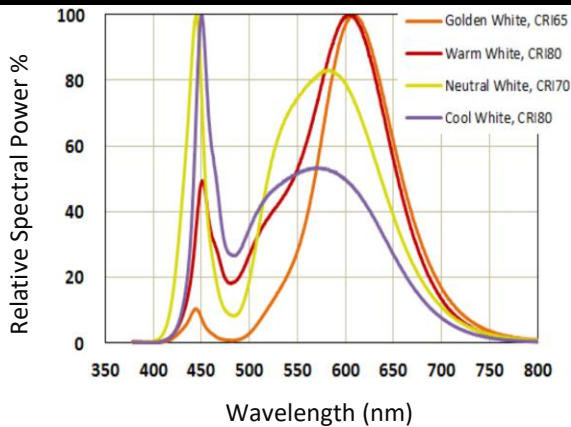
Relative Luminous Flux v.s. Forward Current



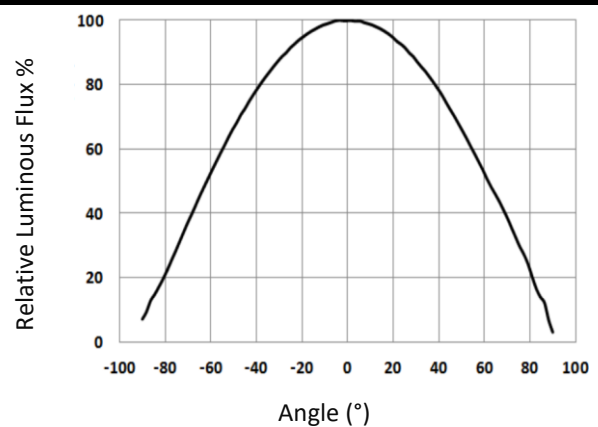
Forward Current v.s. Forward Voltage



Relative Spectral Power v.s. Wavelength

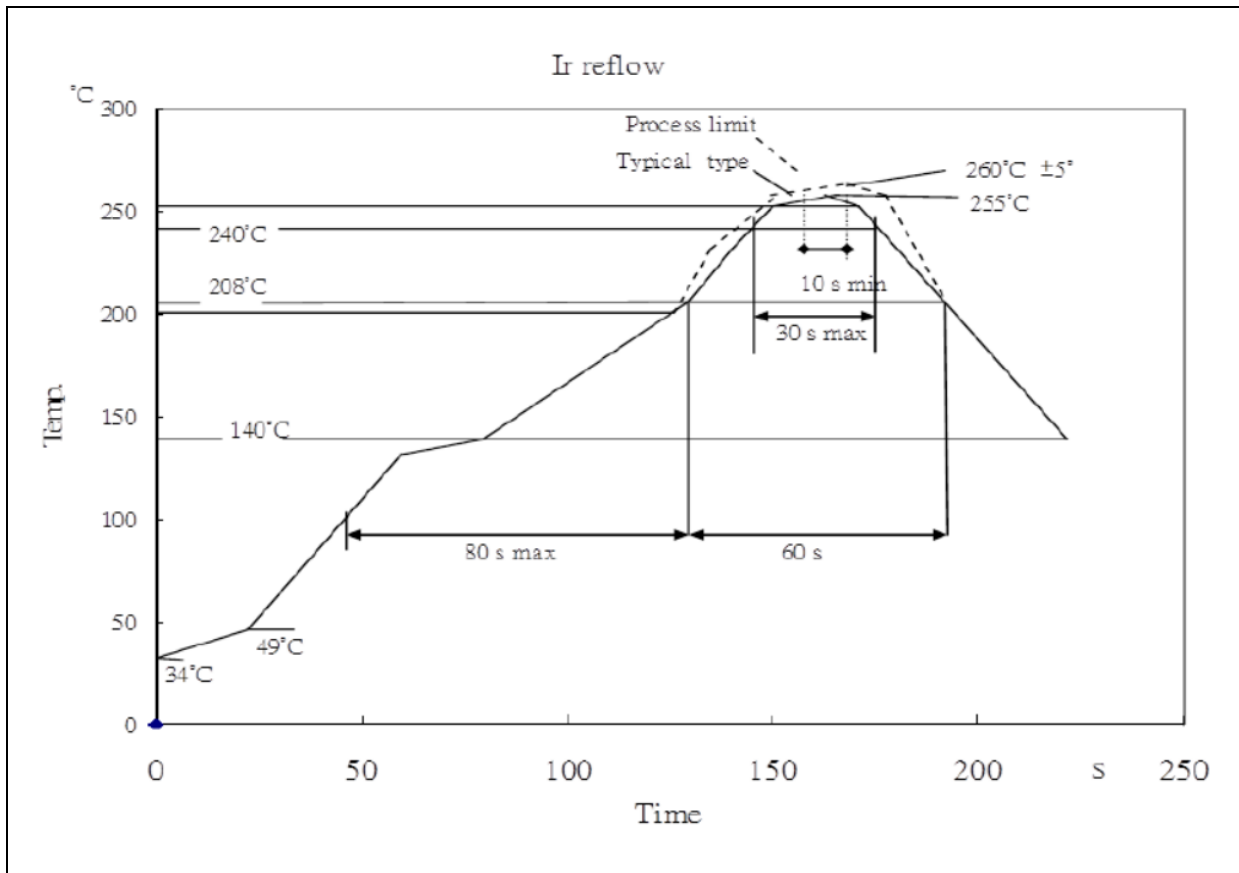


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:

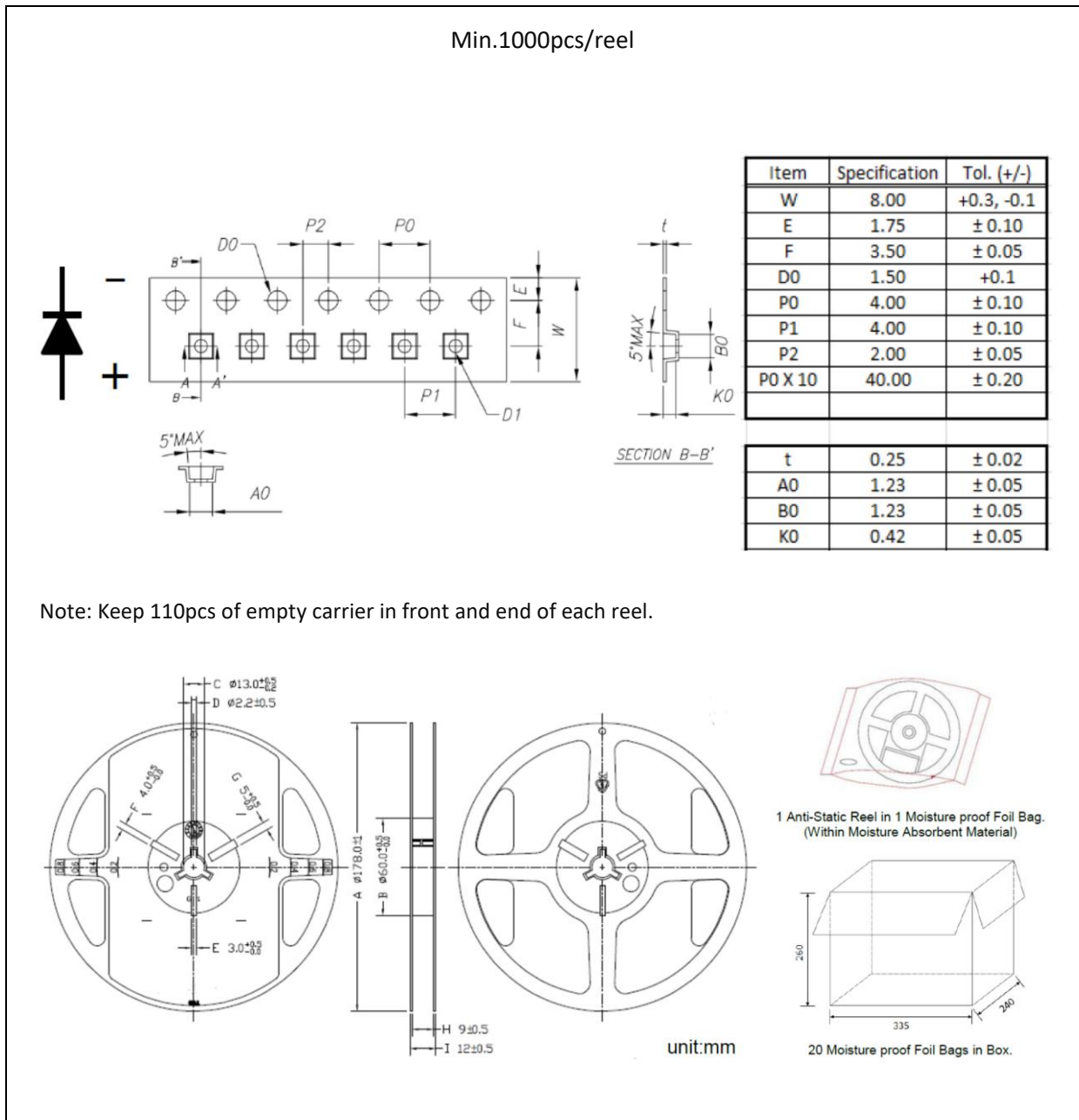


Note:

1. Maxima reflow soldering: 1 time.
2. The recommended reflow temperature is 240°C. The maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	18/03/2020	Datasheet set-up.
A1.1	01/04/2020	Revise flux level and power distribution.
A1.2	04/09/2020	Revise flux level and power distribution.
A1.3	08/10/2020	Add reflow chart.
A1.4	27/09/2021	New datasheet format.